Recent Advances in MEMS Pressure Sensors

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Deadline for manuscript submissions:
closed (15 October 2021)

Message from the Guest Editors

Dear Colleagues,

MEMS pressure sensors are highly demanded in many fields, such as industrial processing, automobiles, daily electronic products, clinical medicine and aerospace, because of their miniature sizes, low power consumption, high sensitivity and ability to be integrated with ICs. In the past few decades, remarkable progress has been achieved in improving their performance, such as sensitivity, resolution, linearity, stability and measuring accuracy. However, with the increasing requirements and expanding scope of practical applications, new challenges are arising that require continuous efforts to address. For instance, low-pressure sensors are required to detect subtle pressure changes in clinical medicine. Ultra-low-pressure sensors are required for monitoring vacuums in MEMS processes. To address these newly raised and unmet requirements in practical applications, this Special Issue aims to collect recent advances in modeling, design, fabrication and packaging technologies for MEMS pressure sensors. Both original research and review papers are welcome.

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mdpi.com/si/75929

Special Issue

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Message from the Editor-in-Chief

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